

PATENT ASSIGNMENT COVER SHEET

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CONVEYING PARTY DATA	
Name	Execution Date
CHIEN-FA LEE	08/31/2018
HSU-SHUI LIU	08/31/2018
JIUN-RONG PAI	09/10/2018
SHOU-WEN KUO	09/10/2018
JIAN-HUNG CHEN	09/03/2018
M.C. LIN	09/04/2018
C.C. CHIEN	09/05/2018
HSUAN LEE	09/06/2018
BORIS HUANG	09/10/2018
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN ROAD 6
Internal Address:	HSINCHU SCIENCE PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15987581
CORRESPONDENCE DATA	
Fax Number:	(215)979-1020
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	215-979-1000
Email:	idocketing@duanemorris.com
Correspondent Name:	DUANE MORRIS LLP (TSMC) IP DEPARTMENT
Address Line 1:	30 SOUTH 17TH STREET
Address Line 4:	PHILADELPHIA, PENNSYLVANIA 19103-4196
ATTORNEY DOCKET NUMBER:	P20172690US00/N1085-01871

NAME OF SUBMITTER:	RICHARD C. KIM
SIGNATURE:	/Richard C. Kim/
DATE SIGNED:	10/19/2018
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ATTORNEY DOCKET NO.: P20172690US00/N1085-01871

ASSIGNMENT AND AGREEMENT

For value received, we, **Chien-Fa LEE, Hsu-Shui LIU, Jiun-Rong PAI, Shou-Wen KUO, Jian-Hung CHEN, M.C. LIN, C. C. CHIEN, Hsuan LEE, and Boris HUANG,** hereby transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Hsinchu Science Park, Hsin-Chu 300-77, Taiwan, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **SYSTEM AND METHOD FOR RING FRAME CLEANING AND INSPECTION**, described in non-provisional patent application S.N. _____ filed _____, and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1

Dated: 8/21/2018

Chien-Fa Lee

Chien-Fa LEE

Address: No. 26, Aly. 14, Ln. 452, Baoshan Rd., East Dist., Hsinchu City 300, Taiwan (R.O.C.)

Inventor No. 2

Dated: 2018.08.31

Hsu Shui Liu

Hsu-Shui LIU

Address: No. 13, Lane 675, Sec. 2, Nanping Rd., Pingjhen City, Taoyuan County 324, Taiwan (R.O.C.)

Inventor No. 3

Dated: 9/10/2018

Jiun-Rong Pai

Jiun-Rong PAI

Address: No. 12, Alley 53, Lane 268, Sinmin Street, Jhubei City, Hsinchu County 302, Taiwan (R.O.C.)

Inventor No. 4

Dated: 9/10/2018

Shou-Wen Kuo

Shou-Wen KUO

Address: 1F, No. 16, Alley 7, Lane 384, Sec. 1, Zhonghua Road, Hsinchu City, Taiwan (R.O.C.)

ATTORNEY DOCKET NO.: P20172690US00/N1085-01871

Inventor No. 5

Dated: 9/3, 2018

Jian-Hung Chen

Jian-Hung CHEN

Address: No. 8, Li-Hsin Road 6, Hsinchu Science Park, Hsin-Chu 300-77, Taiwan (R.O.C.)

Inventor No. 6

Dated: 9/4, 2018

Meng-Chen Lin

M.C. LIN

Address: No. 8, Li-Hsin Road 6, Hsinchu Science Park, Hsin-Chu 300-77, Taiwan (R.O.C.)

Inventor No. 7

Dated: 9/5, 2018

Chung-Hsin Chien

C.C. CHIEN

Address: No. 8, Li-Hsin Road 6, Hsinchu Science Park, Hsin-Chu 300-77, Taiwan (R.O.C.)

Inventor No. 8

Dated: 9/6 '18

Hsuan Lee

Hsuan LEE

Address: 1-1 Nan-Ke N, Rd. Tainan Science Park Tainan, Tainan City 741-44, Taiwan (R.O.C.)

Inventor No. 9

Dated: 9/10 '18

Boris Huang

Boris HUANG

Address: No. 8, Li-Hsin Road 6, Hsinchu Science Park, Hsin-Chu 300-77, Taiwan (R.O.C.)